FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

01-JUL-2004

SUBJECT: ON Semiconductor Final Product/Process Change Notification #13511

TITLE: Qualification of Flipchip International (FCI) for Bumped Products.

EFFECTIVE DATE: 18-AUG-2004

AFFECTED CHANGE CATEGORY: Subcontractor Assembly Site

AFFECTED PRODUCT DIVISION: Logic Products

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or KEN FERGUS, RRST50@onsemi.com >

SAMPLES: Contact your local ON Semiconductor Sales Office or WON KANG, FFP6RB@onsemi.com >

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Office or WON KANG, FFP6RB@onsemi.com >

DISCLAIMER:
Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:
This is the Final PCN to notify customers that the changes described in Initial PCN# 13436, located at www.onsemi.com, have been completed for the NLAS4684FCT1 and NLAS4685FCT1 devices.

ON Semiconductor is pleased to announce that it has successfully completed the bump qualification for FlipChip International (FCI facility located in Phoenix, Arizona as an additional source.
FCI is a fully certified ISO9002 and QS9000 supplier. There will be no changes in the wafer/die source, therefore device functionality will be identical. Device parameters will continue to meet all Data Book specifications, and reliability will continue to meet or exceed ON Semiconductor standards.

This change is classified as a capacity expansion since the products listed below may be bumped at either FCI or the existing ASE qualified site once the final PCN expires.

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RELIABILITY DATA SUMMARY

FCI reliability summary:

Device	Test	Conditions	Results
1. NLAS4685	Temperature Cycle	-65/+150C, 500 cycles	0/90
2. NLAS4685	Temperature Cycle	-65/+150C, 500 cycles	0/90
3. NCP1511	Temperature Cycle	-65/+150C, 500 cycles	0/90
1. NLAS4685	Bump ball shear	In-Line Monitor	0/5
2. NLAS4685	Bump ball shear	In-Line Monitor	0/5
3. NLAS1511	Bump ball shear	In-Line Monitor	0/5

Lot 1 NLAS4685 eutectic Sn/Pb bumps
Lot 2 NLAS4685 pb free Sn/Ag/Cu bumps
Lot 3 NCP1510 eutectic Sn/Pb bumps

ELECTRICAL CHARACTERISTIC SUMMARY

N/A

CHANGED PART IDENTIFICATION

Date Code - WW19, 2004 or later

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AFFECTED DEVICE LIST:

PART
NLAS4684FCT1
NLAS4685FCT1